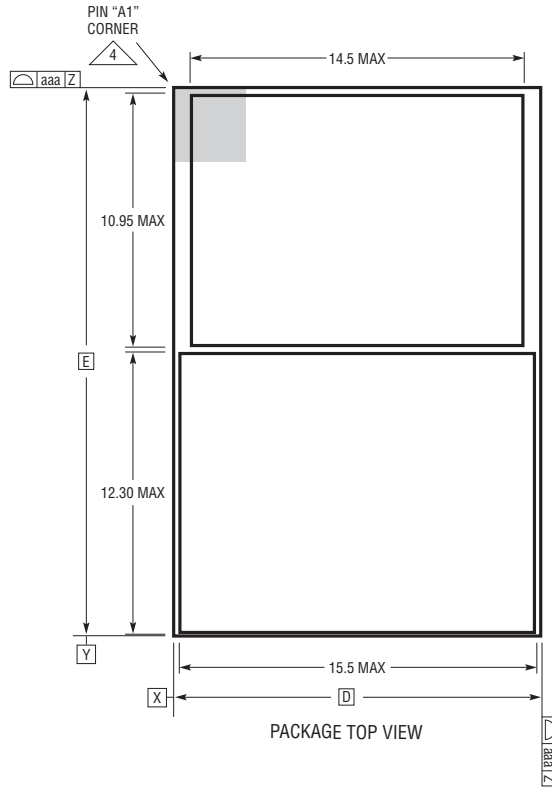
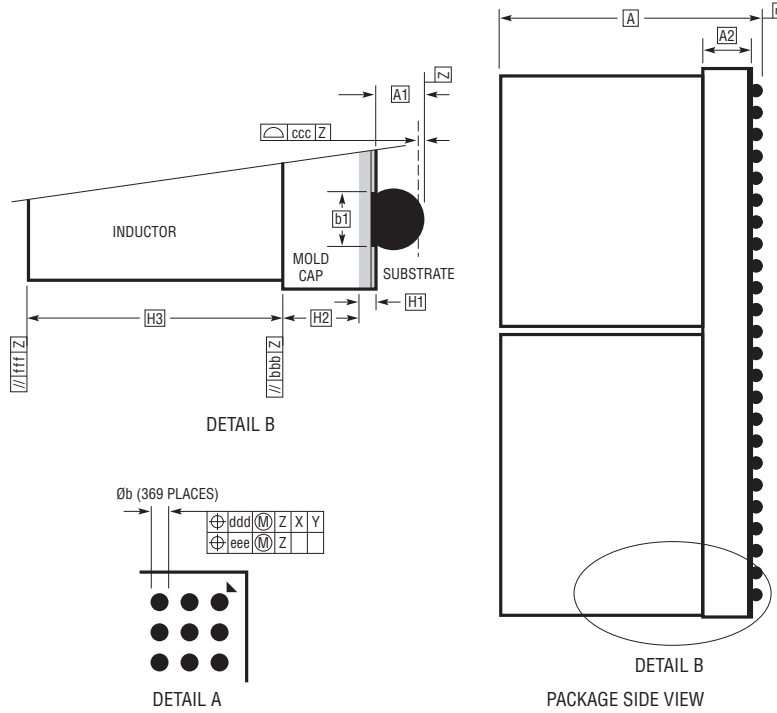


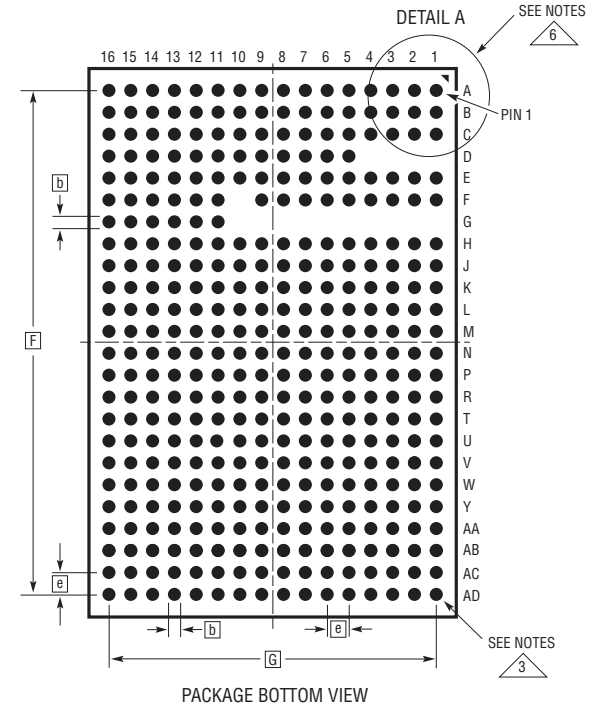
BGA Package
369-Lead (16mm × 24mm × 11.06mm)
 (Reference LTC DWG # 05-08-7045 Rev 0)



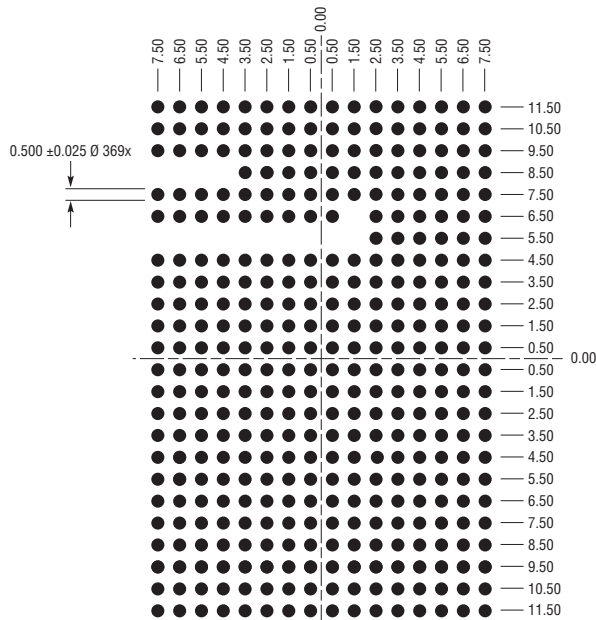
PACKAGE TOP VIEW



PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW



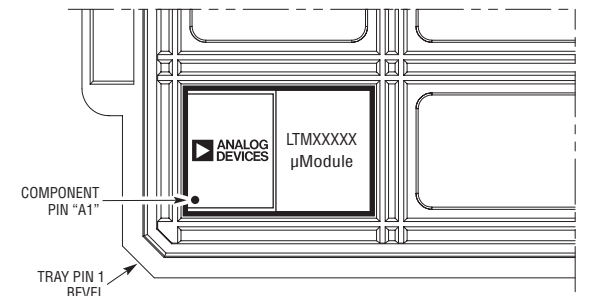
SUGGESTED PCB LAYOUT TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	10.72	11.06	11.39	
A1	0.45	0.50	0.55	BALL HT
A2	1.74	1.84	1.94	
b	0.55	0.60	0.65	BALL DIMENSION
b1	0.475	0.50	0.525	PAD DIMENSION
D		16.00		
E		24.00		
e		1.00		
F		23.00		
G		15.00		
H1	0.29	0.34	0.39	SUBSTRATE THK
H2	1.45	1.50	1.55	MOLD CAP HT
H3	8.53	8.72	8.90	INDUCTOR HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.25	
eee			0.10	
fff			0.35	

TOTAL NUMBER OF BALLS: 369

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
- 3 BALL DESIGNATION PER JESD MS-028 AND JEP95
- 4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
- 6 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION